



**(0,50mm) .01969"**

**BTH, BSH SERIES**

# BASIC BLADE & BEAM HEADER & SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?BTH](http://www.samtec.com?BTH) or [www.samtec.com?BSH](http://www.samtec.com?BSH)

**Insulator Material:**  
LCP



**Contact Material:**  
Phosphor Bronze

**Plating:**  
Au or Sn over 50µ" (1,27µm) Ni

**Current Rating:**  
1.25A @ 80°C ambient

**Flammability Rating:**  
UL 94 V0

**Operating Temp Range:**  
-55°C to +125°C

**Voltage Rating:**  
125 VAC

**Max Cycles:**  
100

**RoHS Compliant:**  
Yes

**Processing:**

**Lead-Free Solderable:**  
Yes

**SMT Lead Coplanarity:**  
(0,10mm) .004" max (030-090)  
(0,15mm) .006" max (120-150)

**Board Stacking:**  
For applications requiring more than two connectors per board or 90 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BSH						
-030, -050, -060, -090, -120, -150						
			-F = Gold Flash on contact, Matte Tin on tail			-K = (7,00mm) .276" DIA Polyimide Film Pick & Place Pad
			-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail			-TR = Tape & Reel (120 positions maximum)
			-C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			



## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

\*Processing conditions will affect mated height.

## APPLICATION SPECIFIC

- 30µ" (0,76µm) Gold
  - Edge Mount Capability
  - 8mm, 11mm, 16mm, 19mm and 22mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11mm, 16mm, 19mm and 22mm not available with 50 positions)
- Call Samtec.

\*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BTH						
-030, -050, -060, -090, -120, -150						
			-F = Gold Flash on contact, Matte Tin on tail			-TR = Tape & Reel (120 positions maximum)
			-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail			
			-C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			

**AGILENT LOGIC ANALYZER TEST POINT CONNECTOR**  
Specify: ASP-65067-01

Due to technical progress, all designs, specifications and components are subject to change without notice.

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